

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	((("6255195") or ("6825532"))).PN.	USPAT	OR	OFF	2005/09/13 10:27
S2	1	("6083324").PN.	USPAT	OR	OFF	2005/09/12 18:06
S3	5	((("5334273") or ("5374564") or ("5661044") or ("5731637") or ("5882987"))).PN.	USPAT	OR	OFF	2005/09/12 18:21
S4	626	gettering with implant\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 18:23
S5	27	S4 and ((donar or support or handle) with wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/12 18:34
S6	161	438/473.ccls.	US-PGPUB; USPAT	OR	ON	2005/09/12 18:34
S7	913	438/58,143,310,402,471-476.ccls.	US-PGPUB; USPAT	OR	ON	2005/09/13 10:28
S8	91	S7 and implant\$5 and bond and ((handle or support or donor or second) with (substrate or wafer))	US-PGPUB; USPAT	OR	ON	2005/09/13 10:29
S9	137	S7 and implant\$5 and bond\$3 and ((handle or support or donor or second) with (substrate or wafer))	US-PGPUB; USPAT	OR	ON	2005/09/13 11:35
S10	1	("6162705").PN.	USPAT	OR	OFF	2005/09/13 11:35
S11	1239	438/455,473.ccls.	US-PGPUB; USPAT	OR	ON	2006/01/08 14:32

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	(implant\$4 and (semiconductor or wafer) and ((select\$3 or known or measur\$3) with depth) and (form\$3 with (amorphous or non\$crystalline)) and (heating or annealing) and (bonding with (handle or second or receiving) with wafer)).CLM.	US-PGPUB	OR	ON	2006/01/08 15:28